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In the Claims

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Please cancel claims 6, 11, 18 and 24 and 25, amend claims 1, 2, 4, 5, 7, 8, 10, 13, 16, 17, 19, 21, 26 and 27 and add claims 28-30 as follows.

1. (Currently Amended) An apparatus for delivering a plurality of chemical vapor deposition fluids to a chemical vapor deposition chamber, comprising: a chemical vapor deposition chamber having a cavity comprising an inlet nozzle, a throat region and an exit nozzle,

said an-inlet nozzle having a first diameter adapted to receive a carrier fluid, and configured to maintain having a first pressure and a first temperature;

said a throat region, having a first and second end, connected to said inlet nozzle at said first end, said throat region having a second diameter less than said first diameter and adapted to receive said carrier fluid from said inlet nozzle, said throat region configured to maintain having a second pressure lower than said first pressure and a second temperature, and having at least a first and a second aperture adjacent to said first and second ends for injecting, respectively, a first and a second chemical vapor deposition dopantfluid into said throat region to allow for atomization of said first and second chemical vapor deposition dopants fluid by said carrier fluid and mixing of said atomized first and second chemical vapor deposition dopants fluid-with said carrier fluid; and, said an-exit nozzle, connected to said throat region at said second end,

having an exit pressure lower than said second pressure and a third

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temperature, said exit nozzle having a third diameter greater than said second diameter to allow for a substantial decrease in pressure from said first pressure to said exit pressure, configured to maintain said exit pressure and a third temperature for said atomized first chemical vapor deposition fluid and said carrier fluid, and configured to introduce said mixed atomized first and second chemical vapor deposition dopants fluid and said carrier fluid in the chemical vapor deposition chamber.



- 1 2. (Currently Amended) The apparatus of claim 1 wherein said inlet nozzle
- 2 having said first diameter is adapted to receive and funnel said carrier fluid to
 - said throat region having said second diameter, said inlet nozzle narrowing at
- 4 an angle in the range of forty to sixty degrees.
- 1 3. (Previously Amended) The apparatus of claim 1 wherein said throat
- region is configured to operate at a critical Mach number of 1.0.
- 1 4. (Currently Amended) The apparatus of claim 1 wherein said second
- 2 pressure and said second temperature are selected to present a condition for
- atomization of said first <u>and second</u> chemical vapor deposition <u>dopantsfluid</u>.
- 1 | 5. (Currently Amended) The apparatus of claim 1 wherein said first and
- 2 second chemical vapor deposition fluid dopants comprise TEOS comprises a
- 3 precursor.

- 1 6. (Canceled.)
- 1 7. (Currently Amended) The apparatus of claim 1 wherein said throat region
- 2 is configured to maintain said first pressure to be greater than said third pressure
- 3 to enhance atomization of said first and second chemical vapor deposition
- 4 fluiddopants.
- 1 8. (Currently Amended) The apparatus of claim 1 wherein said throat
- 2 region is adapted such that said second pressure is lower than said first pressure
- 3 | allowing for said first and second chemical vapor deposition fluid dopants to be
- 4 injected into said throat region.
- 1 9. (Previously Amended) The apparatus of claim 1 wherein said inlet
- 2 nozzle is adapted to receive said carrier fluid at a constant flow rate ensuring
- 3 said second pressure being maintained constant through said throat region.
- 1 | 10. (Currently Amended) The apparatus of claim 61 wherein said first and
- 2 second chemical vapor deposition fluids dopants are introduced simultaneously
- 3 into said throat region without pre-mixing.
- 1 11. (Canceled.).



- 1 12. (Previously Amended) The apparatus of claim 1 wherein said exit nozzle
- 2 expands to said third diameter from said throat region second diameter at an
- 3 angle in the range of twenty to forty degrees.

13. (Currently Amended) An apparatus for delivering a plurality of chemical vapor deposition fluids to a chemical vapor deposition chamber comprising:

a chemical vapor deposition chamber having a cavity comprising an inlet nozzle, a throat region and an exit nozzle,

said an-inlet nozzle having a first diameter adapted to receive a carrier fluid, and configured to maintain having a first pressure and a first temperature, said carrier fluid comprising a process compatible gas selected from the group consisting of O₂, N₂, and He;

said a-throat region, having a first and second end, connected to said inlet nozzle at said first end, said throat region having a second diameter less than said first diameter, and adapted to receive said carrier fluid from said inlet nozzle, said throat region <a href="https://example.com/having-configured-to-maintain-a-second-pressure-and-a-second-temperature-and-having-at-least-a-first-and-a-second-aperture-adjacent-to-said first-and-second-ends-for-injecting, respectively, a first-and-a-second-chemical vapor deposition fluid into said throat region-to-allow for atomization of said first-and-second-chemical vapor deposition fluid by said carrier fluid and mixing of said atomized first-and-second-chemical vapor deposition fluid with said carrier fluid, said first-and-second-chemical vapor deposition fluids

20 comprise fluids selected from the group consisting of precursors and 21 dopants; and, 22 said an-exit nozzle, connected to said throat region at said second end, 23 having said second diameter, said exit nozzle configured to maintain 24 said second pressure and said second temperature, such that said exit nozzle is an extension of said throat region consisting of having the same 25 dimensions as said throat region, said exit region configured 26 introduce said atomized first and second chemical vapor deposition 27 28 fluid and said carrier fluid in said chemical vapor deposition chamber.

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- 1 14. (Previously Amended) The apparatus of claim 13 wherein said inlet
 2 nozzle having said first diameter is adapted to receive and funnel said carrier
 3 fluid to said throat region having said second diameter, said inlet nozzle
 4 narrowing at an angle in the range of forty to sixty degrees.
- 1 15. (Original) The apparatus of claim 13 wherein said throat region is 2 configured to operate at a critical Mach number of 1.0.
 - 16. (Currently Amended) The apparatus of claim 13 wherein said second pressure and said second temperature are selected to present a condition for atomization of said first and second chemical vapor deposition fluid.

- 1 | 17. (Currently Amended) The apparatus of claim 13 wherein said first and
- 2 <u>second</u> chemical vapor deposition fluids comprises <u>TEOS</u> a precursor.
- 1 18. (Canceled.)
- 1 19. (Currently Amended) The apparatus of claim 13 wherein said throat
- 2 region, having said second diameter, is adapted such that said second pressure
- 3 is lower than said first pressure allowing for said first and second chemical
- 4 vapor deposition fluid to be injected into said throat region.
- 1 20. (Previously Amended) The apparatus of claim 13 wherein said inlet
- 2 nozzle is adapted to receive said carrier fluid at a constant flow rate ensuring
- 3 said second pressure being maintained constant through said throat region.
- 1 | 21. (Currently Amended) The apparatus of claim 1318 wherein said first and
- 2 second chemical vapor deposition fluids are introduced simultaneously into
- 3 said throat region without pre-mixing.
- 1 22. (Canceled.)
- 1 23. (Canceled.)
- 1 24. (Canceled.)



1 25. (Canceled.)

26. (Currently Amended) The apparatus of claim 16 wherein said throat region further comprises at least a third aperture for injecting a third chemical vapor deposition fluid-dopant into said throat region to allow for atomization of said third chemical vapor deposition fluid-dopant by said carrier fluid, and allow for mixing of said atomized first, second and third chemical vapor deposition fluids dopants with said carrier fluid.

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27. (Currently Amended) The apparatus of claim 1318 wherein said throat region further comprises at least a third aperture for injecting a third chemical vapor deposition fluid into said throat region to allow for atomization of said third chemical vapor deposition fluid by said carrier fluid, and allow for mixing of said atomized first, second and third chemical vapor deposition fluids with said carrier fluid.

Please add claims 28-30:

- 1 28. (New) An apparatus for delivering a plurality of chemical vapor
- 2 deposition fluids to a chamber, comprising:
- 3 a chemical vapor deposition chamber having a cavity comprising a cross-flow
- 4 injector, said cross-flow injector comprising an inlet nozzle, a throat region and
- 5 an exit nozzle;

said inlet nozzle having a first diameter adapted to receive a carrier fluid, and having a first pressure and a first temperature, said carrier fluid comprising a process compatible gas selected from the group consisting of O₂, N₂, and He; said throat region, having a first and second end, connected to said inlet nozzle at said first end, said throat region having a second diameter less than said first diameter, and adapted to receive said carrier fluid from said inlet nozzle, said throat region having a second pressure and a second temperature and having a first and a second aperture adjacent to said first and second ends for injecting, respectively, a first and a second chemical vapor deposition dopants into said throat region to allow for atomization of said first and second chemical vapor deposition dopants by said carrier fluid and mixing of said atomized first and second chemical vapor deposition dopants with said carrier fluid; and, said exit nozzle, having an exit pressure, connected to said throat region at said second end for receiving said atomized first and second chemical vapor deposition dopants and said carrier fluid; and wherein said chemical vapor deposition chamber is adapted to receive said mixture of atomized first and second chemical vapor deposition dopants with

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1 | 29. (New) The apparatus of claim 28 wherein said exit nozzle has an exit
2 pressure lower than said second pressure and a third temperature, said exit
3 nozzle having a third diameter greater than said second diameter to allow for a

said carrier fluid from said exit nozzle of said cavity.

- 4 substantial decrease in pressure from said first pressure to said exit pressure,
- 5 and configured to introduce said atomized first and second chemical vapor
- 6 deposition dopants and said carrier fluid in the chemical vapor deposition
- 7 chamber.



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30. (New) The apparatus of claim 28 wherein said exit nozzle has said

second pressure and said second temperature, such that said exit nozzle is an

3 extension of said throat region consisting of the same dimensions as said throat

4 region, said exit region being configured to introduce said atomized first and

second chemical vapor deposition dopants and said carrier fluid in said

6 chemical vapor deposition chamber.

In the Drawings

Fig. 2 has been amended. A clean drawing of Fig. 2 is enclosed along with a marked up sheet showing the deletions highlighted in yellow and encircled in red.